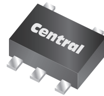
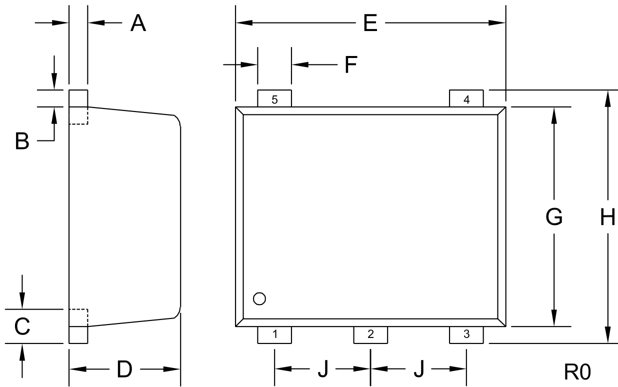
Package Details

SOT-953 Case



Mechanical Drawing



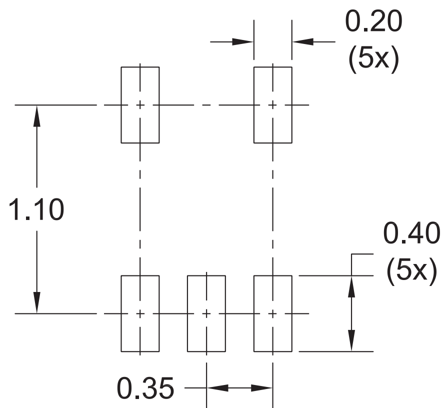
SYMBOL	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.002	0.006	0.050	0.150
B	0.002	0.006	0.050	0.150
C	0.005	0.007	0.125	0.175
D	0.016	0.020	0.400	0.500
E	0.037	0.041	0.950	1.050
F	0.004	0.008	0.100	0.200
G	0.030	0.033	0.750	0.850
H	0.037	0.041	0.950	1.050
J	0.014		0.350	

SOT-953 (REV: R0)

Lead Code:
Reference individual device datasheet.

Part Marking: 2-3 Character Alpha/Numeric Code

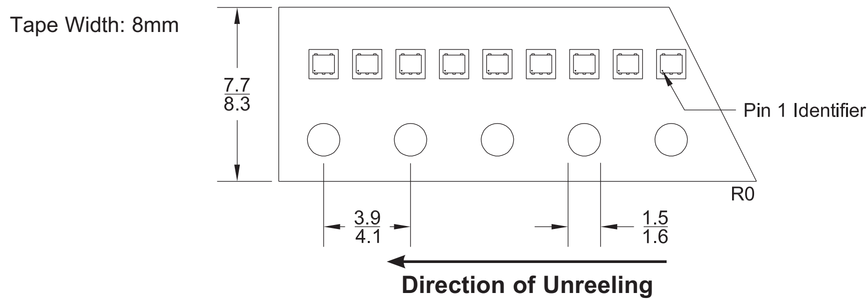
Mounting Pad Geometry (Dimensions in mm)



R1 (4-March 2010)

Package Details
SOT-953 Case

Tape Dimensions and Orientation (Dimensions in mm)



Devices are taped in accordance with Electronic Industries Association Standard EIA-481-1-A

Packaging Base

7” Reel = 8,000 pcs.

Reel Labeling Information

Each reel is labeled with the following information:
Central Part Number, Customer Part Number, Purchase Order Number, Quantity, Lot Number, Date Code, Ship Date and Marking Code.

Reel Packing Information

Reel Size	Reels per Box (Maximum)	Parts per Box (Maximum)	Box Dimensions		Shipping Weight (Max.)	
			INCH	CM	LB	KG
7”	9	72,000	9x9x5	23x23x13	3	2
	18	144,000	9x9x9	23x23x23	6	3
	40	320,000	21x9x9	53x23x23	13	6
	108	864,000	27x9x17	69x23x43	34	16

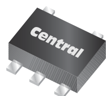
Ordering Information

- For devices taped and reeled on 7” reels, add TR suffix to part number.
- All SMDs are available in small quantities for prototype and manual placement applications.

R1 (4-March 2010)

Material Composition Specification

SOT-953 Case



Device average mass . . . . 0.92 mg

Fluctuation margin . . . . +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	2.07%	0.019	Si	7440-21-3	2.07%	0.019	20,661
bond wire	gold	2.07%	0.019	Au	7440-57-5	2.07%	0.019	20,661
leadframe	Cu alloy	27.42%	0.2522	Cu	7440-50-8	26.86%	0.247	268,595
				Fe	7439-89-6	0.54%	0.005	5,437
				P	7723-14-0	0.01%	0.0001	109
				Zn	7440-66-6	0.01%	0.0001	109
die attach	silver epoxy	1.09%	0.01	Ag	7440-22-4	0.98%	0.009	9,787
				resin filler	Proprietary	0.11%	0.001	1,087
encapsulation	EMC	66.44%	0.611	amorphous silica	7631-86-9	64.38%	0.592	643,758
				epoxy resin	Proprietary	1.96%	0.018	19,574
				carbon	1333-86-4	0.11%	0.001	1,087
plating	Ni/Pd/Au	0.91%	0.0084	Ni	7440-02-0	0.87%	0.008	8,699
				Pd	7440-05-3	0.01%	0.0001	109
				Au	7440-57-5	0.03%	0.0003	326

Disclaimer
The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.